



Microelectronic Packaging & Assembly Solutions

Press Release

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FOR IMMEDIATE RELEASE
9 A.M. EDT, June 1, 2011

QUIK-PAK EXPANDS NEW Open-molded PLASTIC PACKAGE (OmPP) PRODUCT FAMILY

San Diego, CA, June 1, 2011 - Quik-Pak, a division of Delphon Industries and leader in Microelectronic Packaging and Assembly, announced today its exclusive Open-molded Plastic Package (OmPP)[™]. The product family includes pre-molded QFN (Quad Flat No-Lead) and SOIC package configurations that are designed to provide a high quality, quick, and cost-effective solution for your IC packaging and assembly needs.

Quik-Pak's Ni/Au plated QFN's are offered in a broad assortment of body sizes from 3x3mm to 12x12mm with pitches including 0.40mm, 0.50mm and 0.80mm. Custom designs are available. Contact Quik-Pak for details.

Quik-Pak's new OmPP packages are of unsurpassed quality and can be used in production beyond prototype builds. Most will be

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available for rapid delivery to meet customers' timelines and specifications.

.About Quik-Pak:

The company specializes in microelectronic packaging and advanced assembly services. A limitless array of open-cavity and open molded packages are available with no minimum quantity. Packaging can be provided as part of a turnkey assembly solution along with backgrinding, wafer dicing, die/wire bonding, laser micromachining, remolding and marking/branding. Custom assembly expertise includes working with ceramic packages, flip chip die, chip-on-board, stacked die, radiation detectors and MEMS devices. Quik-Pak's unique offerings deliver faster time to market and reduced costs for new devices, while providing excellent flexibility, quality and customer service.

For further information:

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